

SSG4462N-VB Datasheet N-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^d	Q _g (Typ.)			
60	0.012 at V _{GS} = 10 V	12	10.5 nC			
00	0.015 at V _{GS} = 4.5 V	11	10.5110			

FEATURES

 Halogen-free According to IEC 61249-2-21 Definition

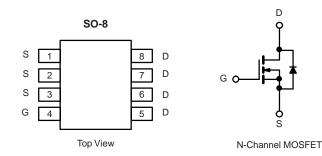


- Trench Power MOSFET
- Optimized for "Low Side" Synchronous Rectifier Operation
- 100 % R_g and UIS Tested





· CCFL Inverter



Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	60	V		
Gate-Source Voltage		V_{GS}	± 20	v	
	T _C = 25 °C		12 ^a		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		11		
Continuous Diain Current (1) = 150 °C)	T _A = 25 °C	l _D	8.0 ^{b, c}		
	T _A = 70 °C		7.6 ^{b, c}		
Pulsed Drain Current	I _{DM}	25	Α		
Continuous Source Drain Diada Current	T _C = 25 °C	I-	4.2		
Continuous Source-Drain Diode Current	T _A = 25 °C	ls —	2.1 ^{b, c}		
Avalanche Current	1 04	I _{AS}	15		
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	11.2	mJ	
	T _C = 25 °C		5		
Mayimum Dayar Dissination	T _C = 70 °C	P _D	3.2	W	
Maximum Power Dissipation	T _A = 25 °C		2.5 ^{b, c}	vv	
	T _A = 70 °C		1.6 ^{b, c}		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	38	50	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	20	25	C/VV	

Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under Steady State conditions is 85 °C/W.



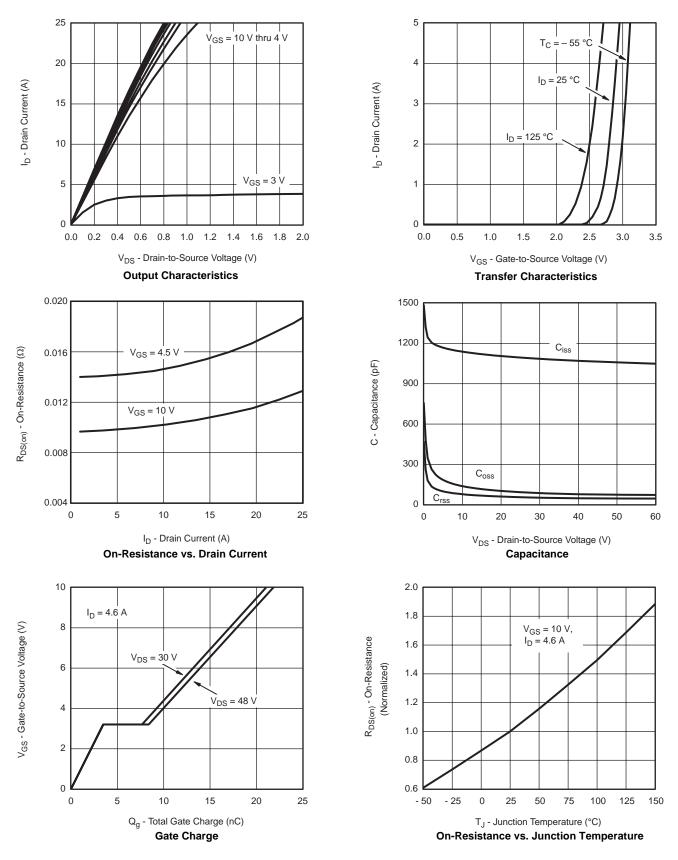
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$	60			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 250		55		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 6.3			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0		3.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zana Cata Valtana Busin Comment		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V, T _J = 55 °C			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	25			Α	
		V _{GS} = 10 V, I _D = 4.6 A		0.012		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 4.2 A		0.015			
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_D = 4.6 \text{ A}$		20		S	
Dynamic ^b							
Input Capacitance	C _{iss}			1100		pF	
Output Capacitance	C _{oss}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		90			
Reverse Transfer Capacitance	C _{rss}			55			
T. 10 . 0		$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 4.6 \text{ A}$		21	1 32	· 	
Total Gate Charge	Q _g			10.5	16	. 0	
Gate-Source Charge	Q _{gs}	$V_{DS} = 30 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 4.6 \text{ A}$		3.5		nC	
Gate-Drain Charge	Q_{gd}			4.2			
Gate Resistance	R _g	f = 1 MHz		3.3	5	Ω	
Turn-On Delay Time	t _{d(on)}			20	30		
Rise Time	ì,	$V_{DD} = 30 \text{ V}, R_{L} = 5.4 \Omega$		150	225	1	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong 5.6 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		20	30		
Fall Time	ì,	Ţ.		60	90		
Turn-On Delay Time	t _{d(on)}			10	15	ns	
Rise Time	ì,	$V_{DD} = 30 \text{ V}, R_{L} = 5.4 \Omega$		15	25		
Turn-Off DelayTime	t _{d(off)}	$I_{D} \cong 5.6 \text{ A}, V_{GEN} = 10 \text{ V}, R_{g} = 1 \Omega$		25	40		
Fall Time	t _f	_		10	15		
Drain-Source Body Diode Characterist	ics			•			
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			4.2	^	
Pulse Diode Forward Current ^a	I _{SM}	-			25	Α	
Body Diode Voltage	V _{SD}	I _S = 2 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	-		25	50	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			25	50	nC	
Reverse Recovery Fall Time	t _a			19			
Reverse Recovery Rise Time				6		ns	

Notes:

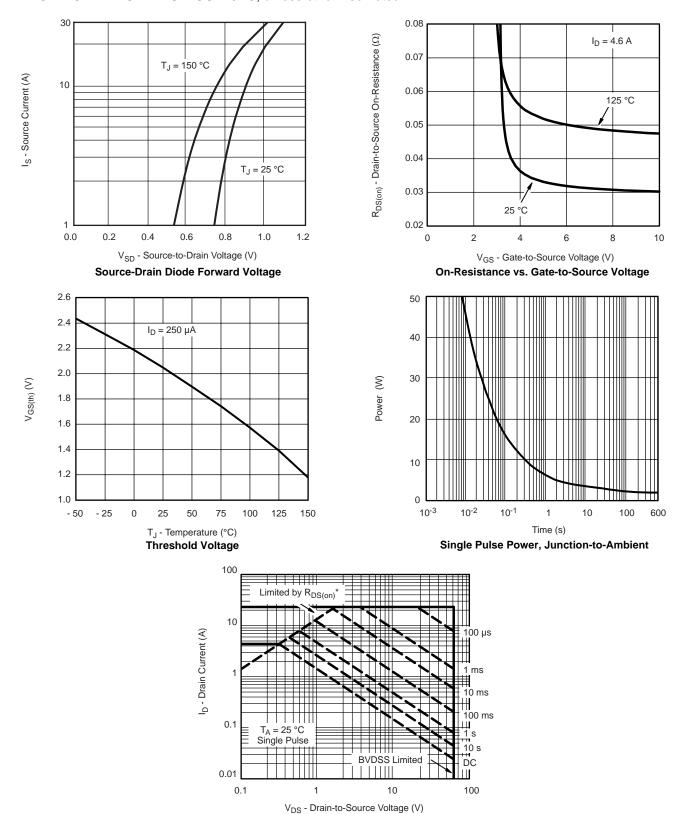
- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





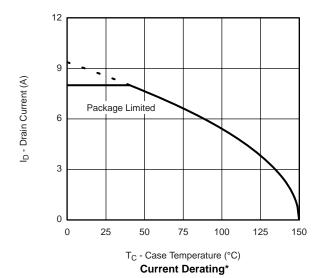


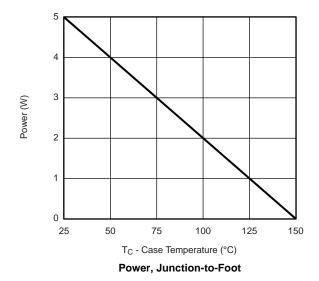


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* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified **Safe Operating Area**

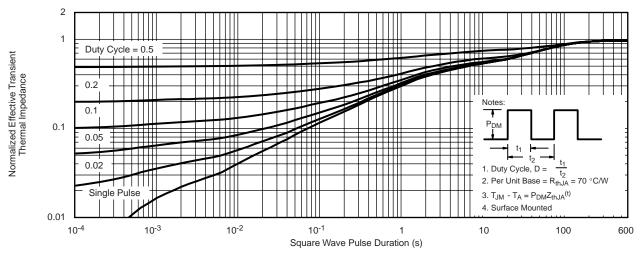




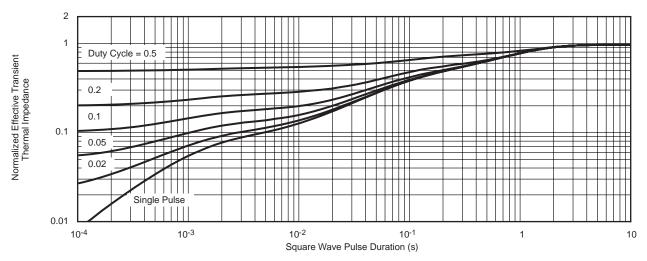


^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient

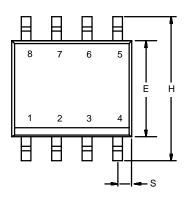


Normalized Thermal Transient Impedance, Junction-to-Foot

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SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012







	MILLIMETERS INCHES			HES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C 06527 Pay 1 11 San 06						

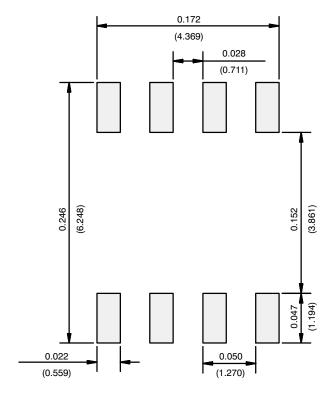
ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498

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RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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